

REMARKS

Reconsideration of the above-identified application in view of the amendments above and remarks below is respectfully requested.

Claims 1-7, 9 to 14 and 16 to 18 are currently before the Examiner. Claims 1, 10 and 13 have been amended and new claims 19 to 22 have been added herein.

Claims 1 to 7, 9, 14, and 16 to 18 stand rejected under 35 U.S.C. 102(b) as being anticipated by Alvino *et al.* (US 4,327,143). The rejection is respectfully traversed.

Specifically, the office action states that Alvino *et al.* disclose a process for preparing a resin coated article comprising contacting a substrate with an accelerated resin composition which includes an epoxy resin, a dicyandiamide or melamine curing agent and an alkali metal containing cure accelerator.

In response, applicants state that claim 1 is directed to a process utilizing an alkali metal containing compound cure accelerator for use with dicyandiamide or a melamine, in an epoxy resin system. In contrast, Alvino *et al.* disclose the deficiencies of dicyandiamide as a curing agent and instead teach a modified dicyandiamide curing agent consisting essentially of the reaction product of dicyandiamide and an aminophylic reagent, which is an aldehyde or an alkyl monoglycidyl ether. Alvino *et al.* utilize the modified dicyandiamide of that invention in Example 2, referenced by the Examiner, with a cure accelerator including benzyldimethylamine and potassium carbonate. Therefore, the present invention differs from Alvino *et al.*, in that the reference does not utilize a dicyandiamide or melamine curing agent with a alkali metal containing compound cure accelerator as currently claimed. Reconsideration is respectfully requested.

Claims 2 to 7, 9, 14, and 16 to 18 incorporate the limitations of claim 1 and are considered patentable over Alvio *et al.* for at least the same reasons. Reconsideration is respectfully requested.

Claims 1 to 4, 9, 10 and 16 to 17 stand rejected under 35 U.S.C. 102(b) as being anticipated by Bagga (US 4,284,574). The rejection is respectfully traversed.

Specifically, the office action states that Bagga discloses a process for preparing a resin coated article comprising contacting a substrate with an accelerated resin composition which includes an epoxy resin, a dicyandiamide or melamine curing agent and an alkali metal containing cure accelerator.

Initially, applicants have amended claim 1 to further define the epoxy resin as a brominated epoxy resin and the cure accelerator as consisting essentially of an alkali metal containing cure accelerator compound. The brominated resin of claim 1 is derived from the reaction of an epihalohydrin and a phenol or a phenol type compound. In contrast Bagga discloses producing low viscosity epoxide resins (of formula IX), by the reaction of a certain di-secondary alcohol (of formula XI), with epichlorohydrin or glycerol 1,3-dichlorohydrine, to form a bis(chlorohydrin) which is then dehydrochlorinated (See col. 4, lines 32-57). Therefore, the present invention differs from Bagga, in that the reference does not derive or utilize a brominated epoxy resin from an epichlorohydrin and a phenol as currently disclosed and claimed. Reconsideration is respectfully requested.

Claims 11 to 14 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Bagga. The rejection is respectfully traversed.

Specifically, the office action states that Bagga discloses the use of alkali metal alkoxides, but fails to specifically disclose where M is lithium, sodium or potassium, R is hydrogen or a C1 to C40 hydrocarbyl group, OR is hydroxyl, methoxy, ethoxy, n-propoxy, i-propoxy, n-butoxy, i-butoxy, s-butoxy, t-butoxy or phenoxy group. The office action concludes

that one skilled in the art would envision these particular compounds based upon the disclosure of alkali metal alkoxides.

Referring to the discussion above, Bagga, being directed to a novel epoxy resin, discloses as interchangeable several classes of curing agents and accelerator compounds. In addition, the resins of Bagga would be relatively expensive to prepare when compared to the claimed brominated epoxy resins which are used in the preparation of typical FR-4 laminate systems, with an amine curing agent and an imidazole cure accelerator. Bagga does not teach or suggest the process of claim 1 or that such process, utilizing a more cost effective alkali metal containing accelerator, would exhibit enhanced thermal properties such as delamination time, delamination temperature, solder resistance and/or thermal degradation temperature, while maintaining a glass transition temperature (T_g) similar to FR-4 laminates. In addition, Bagga does not teach or suggest replacing imidazole cure accelerators entirely with less expensive alkali metal containing accelerators, as in amended claim 10, would result in such enhanced properties. Withdrawal of this rejection is respectfully requested.


New dependent claim 19 further defines the process of claim 1 in that the accelerated resin composition utilized is free of imidazole cure accelerator. New independent claims 20 to 22 utilize the phrase "consisting essentially of" to further define the process of the present invention. Authorization to charge deposit account 50-1863 for any fees associated with the new claims is provided herein.

Claims 5-7 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Bagga in view of Alvino *et al.* The rejection is respectfully traversed.

Referring to the discussions above, claims 5-7 incorporate the limitations of claim 1 and are considered patentable for at least the same reasons. Withdrawal of this rejection is respectfully requested.

In light of the above amendments and remarks, it is respectfully submitted that the pending claims of the present application are in condition for allowance. If the Examiner has any questions or requires additional information, he is invited to contact the undersigned.

Respectfully submitted,



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